

LM139JAN Low Power Low Offset Voltage Quad Comparators

Check for Samples: [LM139JAN](#)

FEATURES

- **Wide Supply Voltage Range 5V to 36 V_{DC} or ±2.5V to ±18 V_{DC}**
- **Very Low Supply Current Drain (0.8 mA) - Independent of Supply Voltage**
- **Low Input Biasing Current: 25 nA**
- **Low Input Offset Current: ±5 nA**
- **Offset Voltage: ±3 mV**
- **Input Common-Mode Voltage Range Includes GND**
- **Differential Input Voltage Range Equal to the Power Supply Voltage**
- **Low Output Saturation Voltage: 250 mV at 4 mA**
- **Output Voltage Compatible with TTL, DTL, ECL, MOS and CMOS Logic Systems**

ADVANTAGES

- **High Precision Comparators**
- **Reduced V_{OS} Drift Over Temperature**
- **Eliminates Need for Dual Supplies**
- **Allows Sensing Near GND**
- **Compatible with All Forms of Logic**
- **Power Drain Suitable for Battery Operation**

DESCRIPTION

The LM139 consists of four independent precision voltage comparators with an offset voltage specification as low as 2 mV max for all four comparators. These were designed specifically to operate from a single power supply over a wide range of voltages. Operation from split power supplies is also possible and the low power supply current drain is independent of the magnitude of the power supply voltage. These comparators also have a unique characteristic in that the input common-mode voltage range includes ground, even though operated from a single power supply voltage.

Application areas include limit comparators, simple analog to digital converters; pulse, squarewave and time delay generators; wide range VCO; MOS clock timers; multivibrators and high voltage digital logic gates. The LM139 was designed to directly interface with TTL and CMOS. When operated from both plus and minus power supplies, they will directly interface with MOS logic— where the low power drain of the LM139 is a distinct advantage over standard comparators.

Connection Diagrams

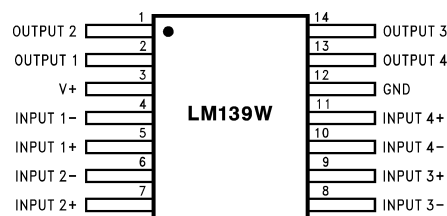


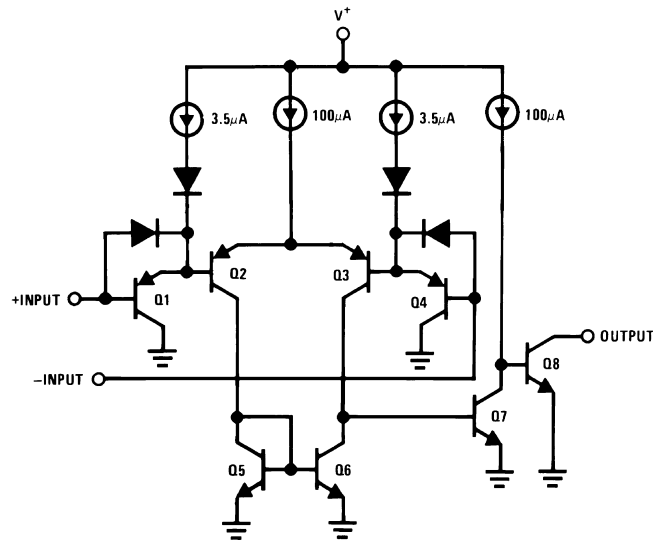
Figure 1. See Package Number NAD0014B



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Schematic Diagram



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾

Supply Voltage, V^{+} ⁽²⁾			36 V_{DC} or $\pm 18 V_{DC}$
Differential Input Voltage ⁽³⁾			36 V_{DC}
Output Voltage			36 V_{DC}
Input Voltage			$-0.3 V_{DC}$ to $+36 V_{DC}$
Input Current ($V_{IN} < -0.3 V_{DC}$) ⁽⁴⁾⁽⁵⁾			50 mA
Power Dissipation ⁽⁶⁾⁽⁷⁾	CLGA		350 mW @ $T_A = 125^{\circ}C$
Output Short-Circuit to GND, ⁽⁸⁾			Continuous
Storage Temperature Range			$-65^{\circ}C \leq T_A \leq +150^{\circ}C$
Maximum Junction Temperature (T_J)			$+175^{\circ}C$
Lead Temperature (Soldering, 10 seconds)			$260^{\circ}C$
Operating Temperature Range			$-55^{\circ}C \leq T_A \leq +125^{\circ}C$
Thermal Resistance	θ_{JA}	CLGA (Still Air)	183 $^{\circ}C/W$
		CLGA (500LF / Min Air flow)	120 $^{\circ}C/W$
	θ_{JC}	CLGA	23 $^{\circ}C/W$
Package Weight (typical)		CLGA	460mg
ESD rating ⁽⁹⁾			600V

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see, the Electrical Characteristics. The ensured specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- (2) Short circuits from the output to V^{+} can cause excessive heating and eventual destruction. When considering short circuits to ground, the maximum output current is approximately 20mA independent of the magnitude of V^{+} .
- (3) Positive excursions of input voltage may exceed the power supply level. As long as the other voltage remains within the common-mode range, the comparator will provide a proper output state. The low input voltage state must not be less than $-0.3 V_{DC}$ (or $0.3 V_{DC}$ below the magnitude of the negative power supply, if used) (at $25^{\circ}C$).
- (4) This input current will only exist when the voltage at any of the input leads is driven negative. It is due to the collector-base junction of the input PNP transistors becoming forward biased and thereby acting as input diode clamps. In addition to this diode action, there is also lateral NPN parasitic transistor action on the IC chip. This transistor action can cause the output voltages of the comparators to go to the V^{+} voltage level (or to ground for a large overdrive) for the time duration that an input is driven negative. This is not destructive and normal output states will re-establish when the input voltage, which was negative, again returns to a value greater than $-0.3 V_{DC}$ (at $25^{\circ}C$).
- (5) The direction of the input current is out of the IC due to the PNP input stage. This current is essentially constant, independent of the state of the output so no loading change exists on the reference or input lines.
- (6) The low bias dissipation and the ON-OFF characteristics of the outputs keeps the chip dissipation very small ($P_D \leq 100mW$), provided the output transistors are allowed to saturate.
- (7) The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{Jmax} (maximum junction temperature), θ_{JA} (Package junction to ambient thermal resistance), and T_A (ambient temperature). The maximum allowable power dissipation at any temperature is $P_{Dmax} = (T_{Jmax} - T_A) / \theta_{JA}$ or the number given in the Absolute Maximum Ratings, whichever is lower.
- (8) Short circuits from the output to V^{+} can cause excessive heating and eventual destruction. When considering short circuits to ground, the maximum output current is approximately 20 mA independent of the magnitude of V^{+} .
- (9) Human Body model, 1.5 K Ω in series with 100 pF

Quality Conformance Inspection

Mil-Std-883, Method 5005 - Group A

Subgroup	Description	Temp ($^{\circ}C$)
1	Static tests at	+25
2	Static tests at	+125
3	Static tests at	-55
4	Dynamic tests at	+25
5	Dynamic tests at	+125
6	Dynamic tests at	-55
7	Functional tests at	+25
8A	Functional tests at	+125
8B	Functional tests at	-55
9	Switching tests at	+25
10	Switching tests at	+125

Quality Conformance Inspection (continued)

Mil-Std-883, Method 5005 - Group A

Subgroup	Description	Temp (°C)
11	Switching tests at	-55

LM139 JAN Electrical Characteristics DC Parameters

The following conditions apply, unless otherwise specified. $-V_{CC} = 0V$

Symbol	Parameters	Conditions	Notes	Min	Max	Unit	Sub-groups
V_{IO}	Input Offset Voltage	$+V_{CC} = 30V, V_O = 15V$		-5.0	5.0	mV	1
				-7.0	7.0	mV	2, 3
		$+V_{CC} = 2V, -V_{CC} = -28V, V_O = -13V$		-5.0	5.0	mV	1
				-7.0	7.0	mV	2, 3
		$+V_{CC} = 5V, V_O = 1.4V$		-5.0	5.0	mV	1
				-7.0	7.0	mV	2, 3
I_{IO}	Input Offset Current	$+V_{CC} = 30V, R_S = 20K\Omega, V_O = 15V$	See ⁽¹⁾	-25	25	nA	1, 2
			See ⁽¹⁾	-75	75	nA	3
		$+V_{CC} = 2V, -V_{CC} = -28V, R_S = 20K\Omega, V_O = -13V$	See ⁽¹⁾	-25	25	nA	1, 2
			See ⁽¹⁾	-75	75	nA	3
		$+V_{CC} = 5V, R_S = 20K\Omega, V_O = 1.4V$	See ⁽¹⁾	-25	25	nA	1, 2
			See ⁽¹⁾	-75	75	nA	3
$\pm I_{IB}$	Input Bias Current	$+V_{CC} = 30V, R_S = 20K\Omega, V_O = 15V$	See ⁽¹⁾	-100	+0.1	nA	1, 2
			See ⁽¹⁾	-200	+0.1	nA	3
		$+V_{CC} = 2V, -V_{CC} = -28V, R_S = 20K\Omega, V_O = -13V$	See ⁽¹⁾	-100	+0.1	nA	1, 2
			See ⁽¹⁾	-200	+0.1	nA	3
		$+V_{CC} = 5V, R_S = 20K\Omega, V_O = 1.4V$	See ⁽¹⁾	-100	+0.1	nA	1, 2
			See ⁽¹⁾	-200	+0.1	nA	3
$+V_{CC} = 2V, -V_{CC} = -3V, R_S = 20K\Omega, V_O = -1.6V$	See ⁽¹⁾	-100	+0.1	nA	1, 2		
	See ⁽¹⁾	-200	+0.1	nA	3		
CMRR	Input Voltage Common Mode Rejection	$+V_{CC} = 30V$		76		dB	1, 2, 3
		$+V_{CC} = 5V$		70		dB	1, 2, 3
I_{CEX}	Output Leakage	$+V_{CC} = 30V, V_O = +30V$			1.0	μA	1, 2, 3
$+I_{IL}$	Input Leakage Current	$+V_{CC} = 36V, V + i = 34V, V - i = 0V$		-500	500	nA	1, 2, 3
$-I_{IL}$	Input Leakage Current	$+V_{CC} = 36V, V + i = 0V, V - i = 34V$		-500	500	nA	1, 2, 3
V_{OL}	Logical "0" Output Voltage	$+V_{CC} = 4.5V, I_O = 4mA$			0.4	V	1
					0.7	V	2, 3
		$+V_{CC} = 4.5V, I_O = 8mA$			1.5	V	1
					2.0	V	2, 3
I_{CC}	Power Supply Current	$+V_{CC} = 5V, V_{ID} = 15mV$			2.0	mA	1, 2
					3.0	mA	3
		$+V_{CC} = 30V, V_{ID} = 15mV$			3.0	mA	1, 2
					4.0	mA	3

(1) S/S $R_S = 20K\Omega$, tested at $R_S = 10K\Omega$ as equivalent test.

LM139 JAN Electrical Characteristics DC Parameters (continued)

 The following conditions apply, unless otherwise specified. $-V_{CC} = 0V$

Symbol	Parameters	Conditions	Notes	Min	Max	Unit	Sub-groups
$\Delta V_{IO} / \Delta T$	Temperature Coefficient of Input Offset Voltage	$25^{\circ}C \leq T_A \leq 125^{\circ}C$	See ⁽²⁾	-25	25	$\mu V/^{\circ}C$	2
		$-55^{\circ}C \leq T_A \leq 25^{\circ}C$	See ⁽²⁾	-25	25	$\mu V/^{\circ}C$	3
$\Delta I_{IO} / \Delta T$	Temperature Coefficient of Input Offset Current	$25^{\circ}C \leq T_A \leq 125^{\circ}C$	See ⁽²⁾	-300	300	$pA/^{\circ}C$	2
		$-55^{\circ}C \leq T_A \leq 25^{\circ}C$	See ⁽²⁾	-400	400	$pA/^{\circ}C$	3
A_{VS}	Open Loop Voltage Gain	$+V_{CC} = 15V, R_L = 15K\Omega,$ $1V \leq V_O \leq 11V$	See ⁽³⁾	50		V/mV	4
			See ⁽³⁾	25		V/mV	5, 6
V_{IO}	Tempco Screen				4.0	mV	
CMRR	Tempco Screen				70	dB	
I_{IO}	Tempco Screen				13	nA	
I_{IB}	Tempco Screen				12	nA	

(2) Calculated parameter; for Delta $V_{IO} / \Delta T$ use V_{IO} test at $+V_{CC} = 30V, -V_{CC} = 0V, V_O = 15V$; and for Delta $I_{IO} / \Delta T$ use I_{IB} test at $+V_{CC} = 30V, -V_{CC} = 0V, V_O = 15V$

(3) Datalog of $K = V/mV$.

LM139 JAN Electrical Characteristics AC Parameters

Symbol	Parameters	Conditions	Notes	Min	Max	Unit	Sub-groups
t_{RLH}	Response Time: Low-to-High	$+V_{CC} = 5V, V_I = 100mV,$ $R_L = 5.1K\Omega, V_{OD} = 5mV$			5.0	μS	7, 8B
					7.0	μS	8A
		$+V_{CC} = 5V, V_I = 100mV,$ $R_L = 5.1K\Omega, V_{OD} = 50mV$			0.8	μS	7, 8B
					1.2	μS	8A
t_{RHL}	Response Time: High-to-Low	$+V_{CC} = 5V, V_I = 100mV,$ $R_L = 5.1K\Omega, V_{OD} = 5mV$			2.5	μS	7, 8B
					3.0	μS	8A
		$+V_{CC} = 5V, V_I = 100mV,$ $R_L = 5.1K\Omega, V_{OD} = 50mV$			0.8	μS	7, 8B
					1.0	μS	8A
C_S	Channel Separation	$+V_{CC} = 20V, -V_{CC} = -10V,$ A to B		80		dB	7
		$+V_{CC} = 20V, -V_{CC} = -10V,$ A to C		80		dB	7
		$+V_{CC} = 20V, -V_{CC} = -10V,$ A to D		80		dB	7
		$+V_{CC} = 20V, -V_{CC} = -10V,$ B to A		80		dB	7
		$+V_{CC} = 20V, -V_{CC} = -10V,$ B to C		80		dB	7
		$+V_{CC} = 20V, -V_{CC} = -10V,$ B to D		80		dB	7
		$+V_{CC} = 20V, -V_{CC} = -10V,$ C to A		80		dB	7
		$+V_{CC} = 20V, -V_{CC} = -10V,$ C to B		80		dB	7
		$+V_{CC} = 20V, -V_{CC} = -10V,$ C to D		80		dB	7
		$+V_{CC} = 20V, -V_{CC} = -10V,$ D to A		80		dB	7
		$+V_{CC} = 20V, -V_{CC} = -10V,$ D to B		80		dB	7
		$+V_{CC} = 20V, -V_{CC} = -10V,$ D to C		80		dB	7
		V_{LAT}	Voltage Latch (Logical "1" Input)	$+V_{CC} = 5V, V_I = 10V,$ $I_O = 4mA$			0.4

LM139 JAN Electrical Characteristics DC Parameters Drift Values

The following conditions apply, unless otherwise specified. $-V_{CC} = 0V$
Delta calculations performed on JAN S product at Group B, Subgroup 5.

Symbol	Parameters	Conditions	Notes	Min	Max	Unit	Sub-groups
V_{IO}	Input Offset Voltage	$V_{CC} = 30V, V_O = 15V$		-1.0	1.0	mV	1
$\pm I_{Bias}$	Input Bias Current	$V_{CC} = 30V, R_S = 20K\Omega,$ $V_O = 15V$		-15	15	nA	1

Typical Performance Characteristics

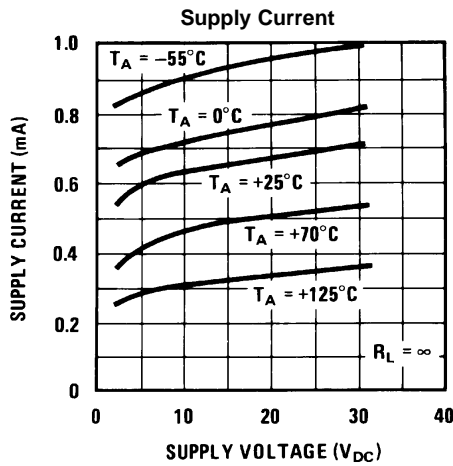


Figure 2.

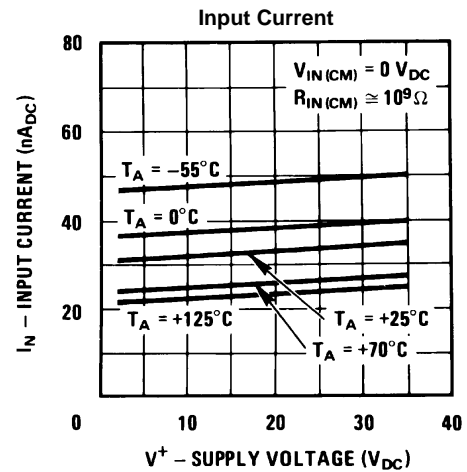


Figure 3.

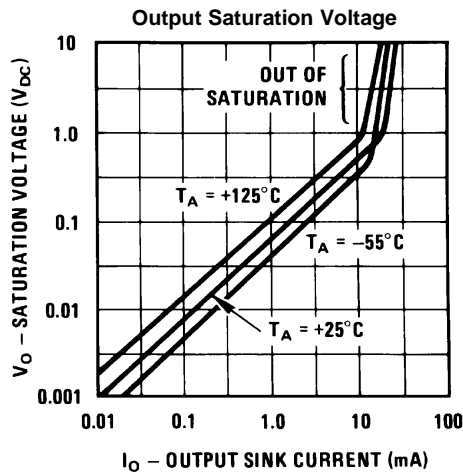


Figure 4.

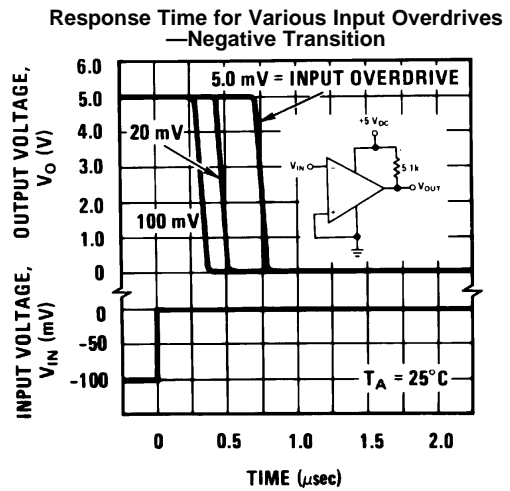


Figure 5.

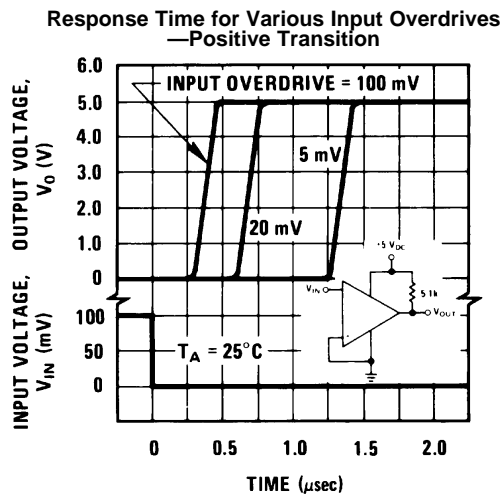


Figure 6.

APPLICATION HINTS

The LM139 is a high gain, wide bandwidth device which, like most comparators, can easily oscillate if the output lead is inadvertently allowed to capacitively couple to the inputs via stray capacitance. This shows up only during the output voltage transition intervals as the comparator changes states. Power supply bypassing is not required to solve this problem. Standard PC board layout is helpful as it reduces stray input-output coupling. Reducing the input resistors to $< 10\text{ k}\Omega$ reduces the feedback signal levels and finally, adding even a small amount (1 to 10 mV) of positive feedback (hysteresis) causes such a rapid transition that oscillations due to stray feedback are not possible. Simply socketing the IC and attaching resistors to the pins will cause input-output oscillations during the small transition intervals unless hysteresis is used. If the input signal is a pulse waveform, with relatively fast rise and fall times, hysteresis is not required.

All pins of any unused comparators should be tied to the negative supply.

The bias network of the LM139 establishes a drain current which is independent of the magnitude of the power supply voltage over the range of from 5 V_{DC} to 30 V_{DC} .

It is usually unnecessary to use a bypass capacitor across the power supply line.

The differential input voltage may be larger than V^+ without damaging the device. Protection should be provided to prevent the input voltages from going negative more than $-0.3\text{ V}_{\text{DC}}$ (at 25°C). An input clamp diode can be used as shown in the applications section.

The output of the LM139 is the uncommitted collector of a grounded-emitter NPN output transistor. Many collectors can be tied together to provide an output OR'ing function. An output pull-up resistor can be connected to any available power supply voltage within the permitted supply voltage range and there is no restriction on this voltage due to the magnitude of the voltage which is applied to the V^+ terminal of the LM139 package. The output can also be used as a simple SPST switch to ground (when a pull-up resistor is not used). The amount of current which the output device can sink is limited by the drive available (which is independent of V^+) and the β of this device. When the maximum current limit is reached (approximately 16 mA), the output transistor will come out of saturation and the output voltage will rise very rapidly. The output saturation voltage is limited by the approximately $60\Omega\text{ R}_{\text{SAT}}$ of the output transistor. The low offset voltage of the output transistor (1 mV) allows the output to clamp essentially to ground level for small load currents.

Typical Applications

($V^+ = 5.0\text{ V}_{\text{DC}}$)

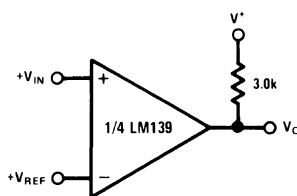


Figure 7. Basic Comparator

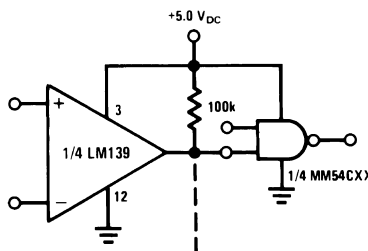


Figure 8. Driving CMOS

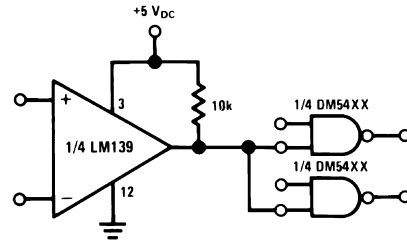


Figure 9. Driving TTL

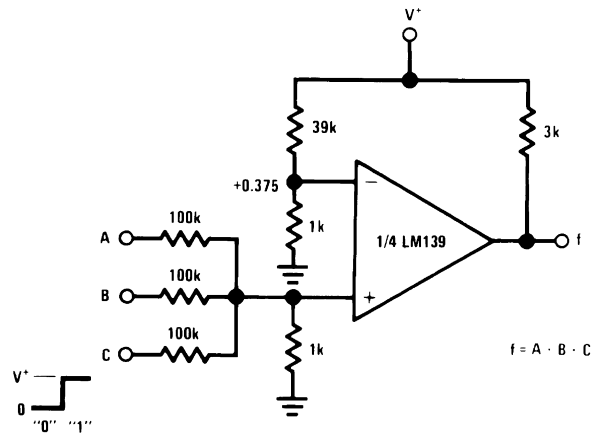


Figure 10. AND Gate

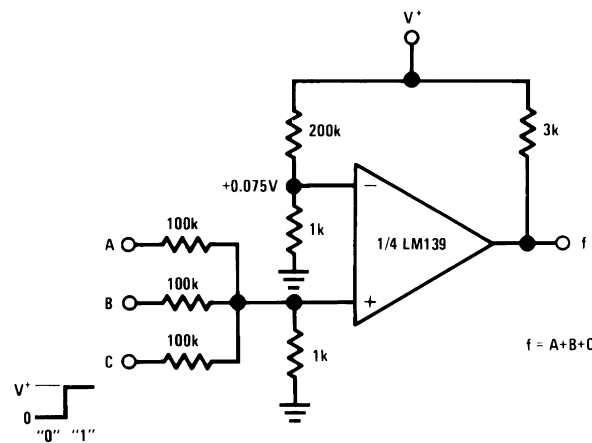


Figure 11. OR Gate

Typical Applications

($V^+ = 15 V_{DC}$)

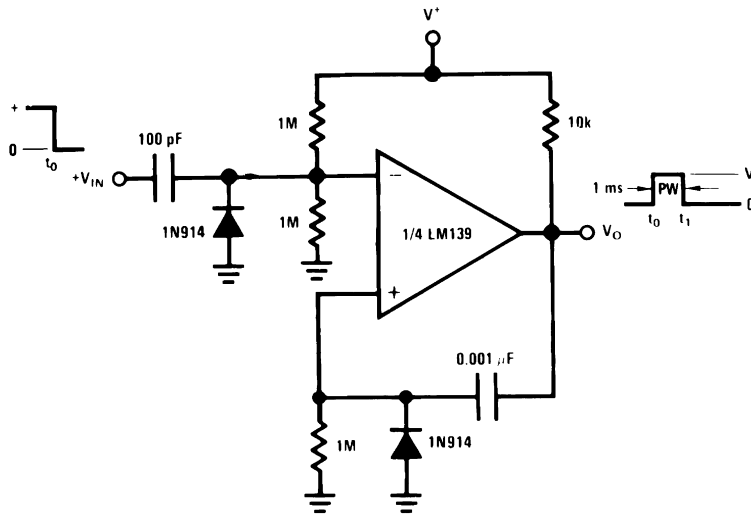


Figure 12. One-Shot Multivibrator

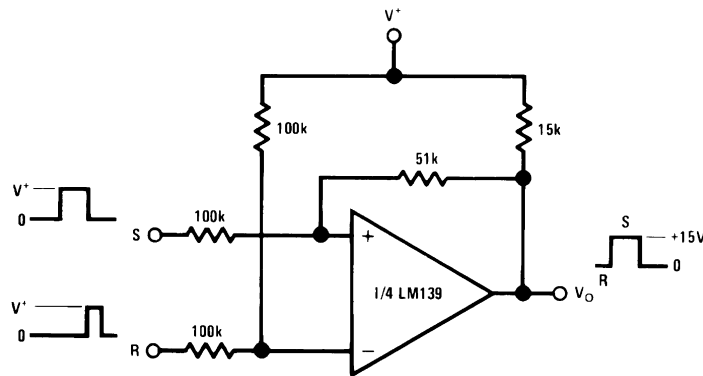


Figure 13. Bi-Stable Multivibrator

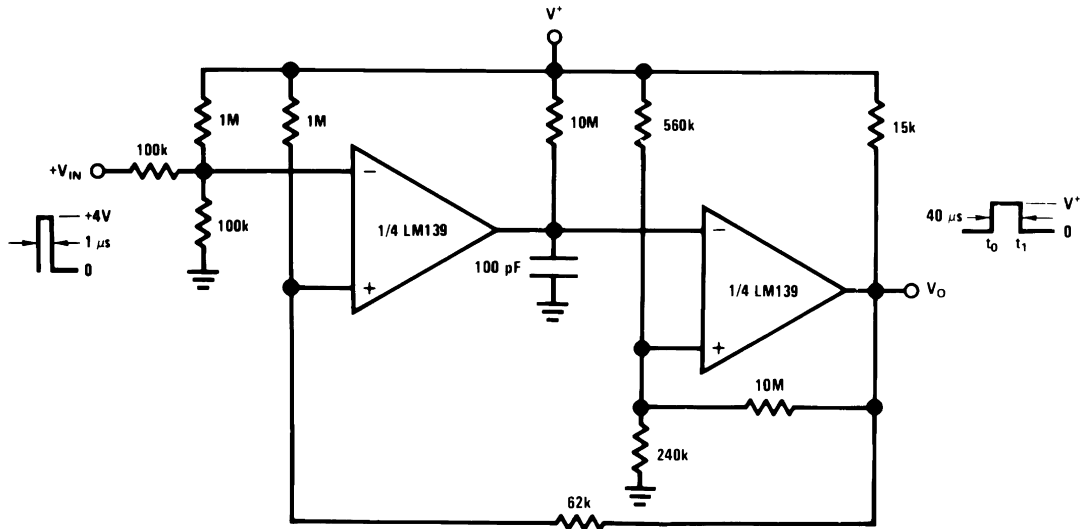


Figure 14. One-Shot Multivibrator with Input Lock Out

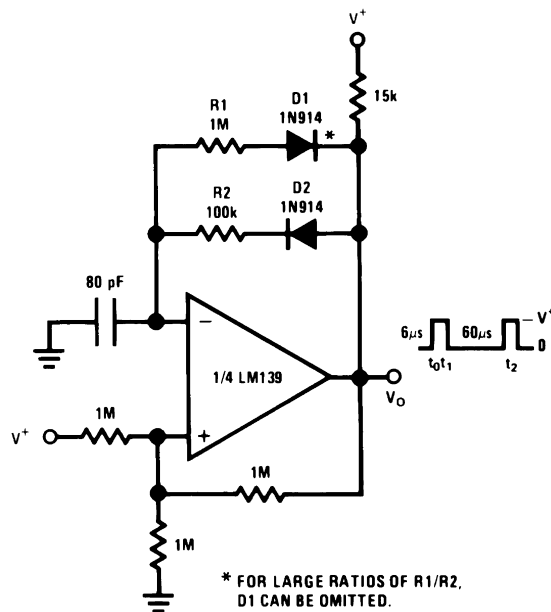


Figure 15. Pulse Generator

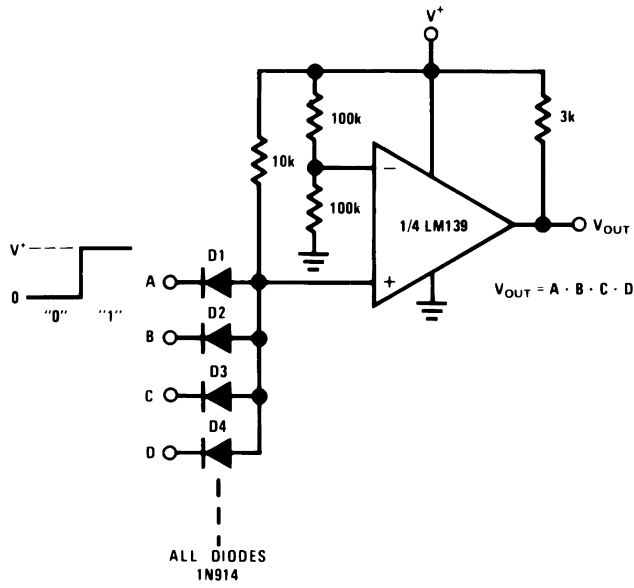


Figure 16. Large Fan-In AND Gate

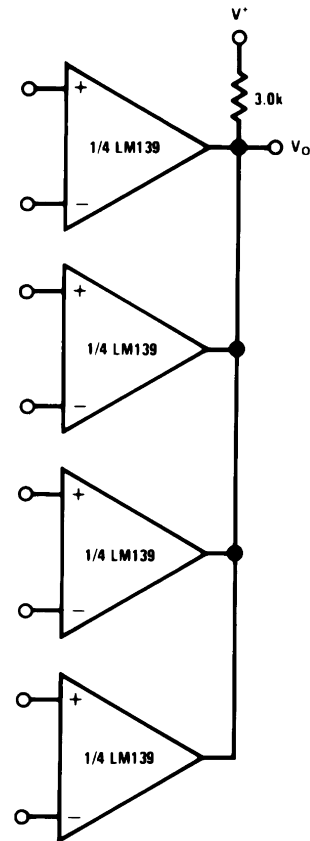


Figure 17. ORing the Outputs

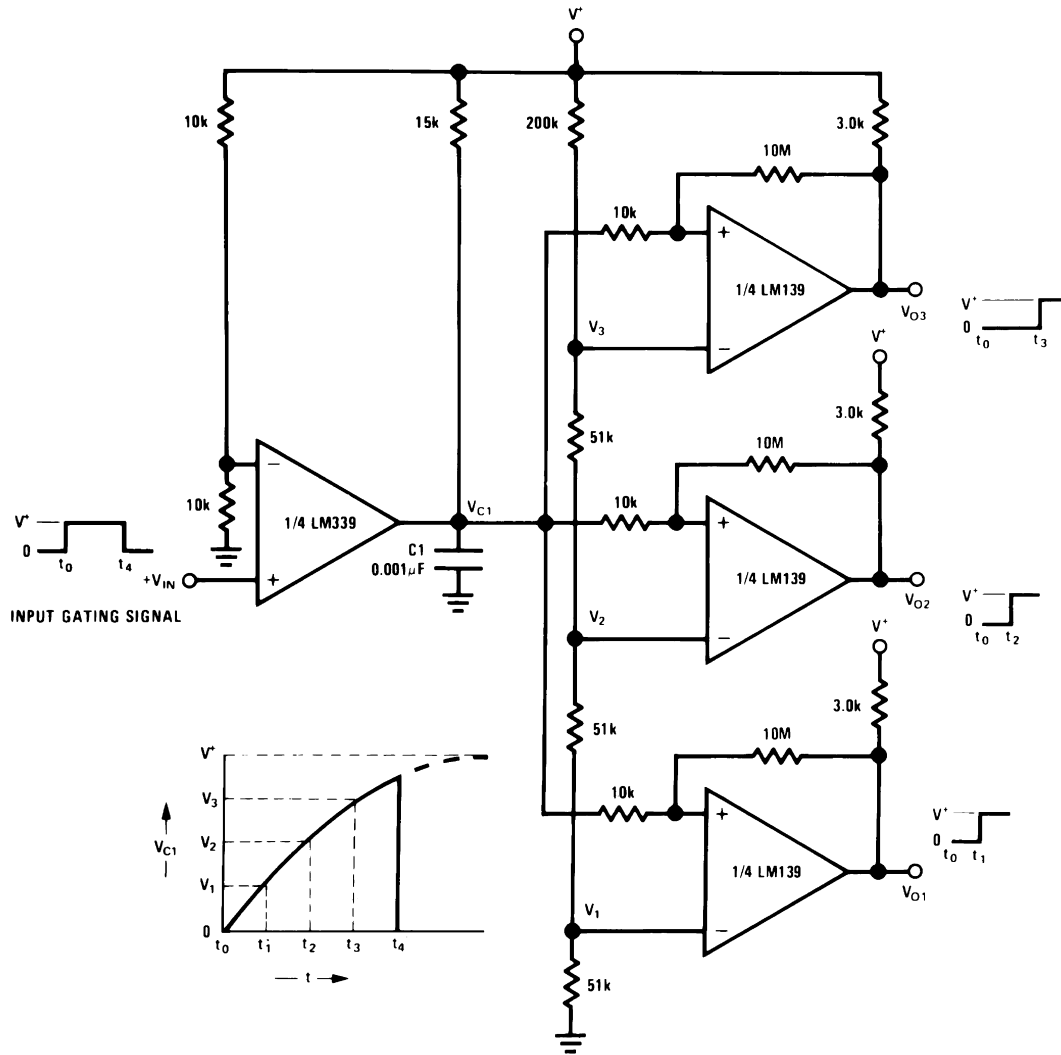


Figure 18. Time Delay Generator

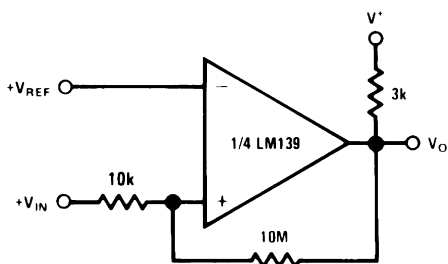


Figure 19. Non-Inverting Comparator with Hysteresis

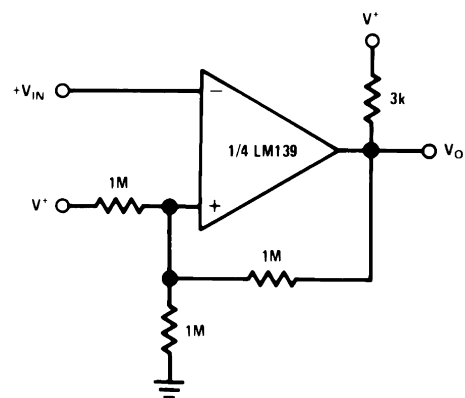


Figure 20. Inverting Comparator with Hysteresis

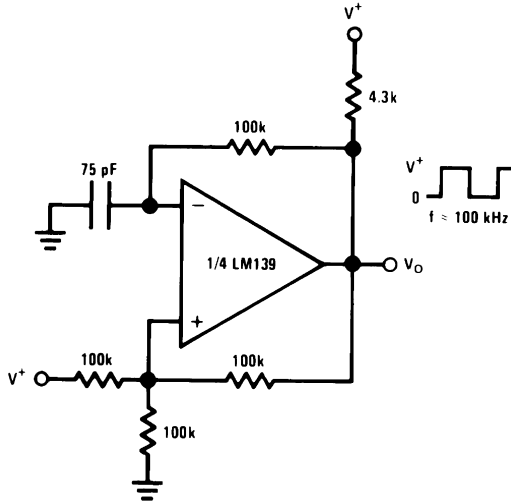


Figure 21. Squarewave Oscillator

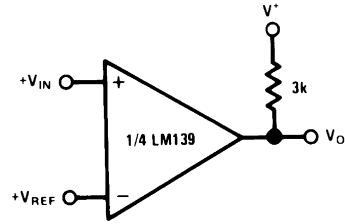


Figure 22. Basic Comparator

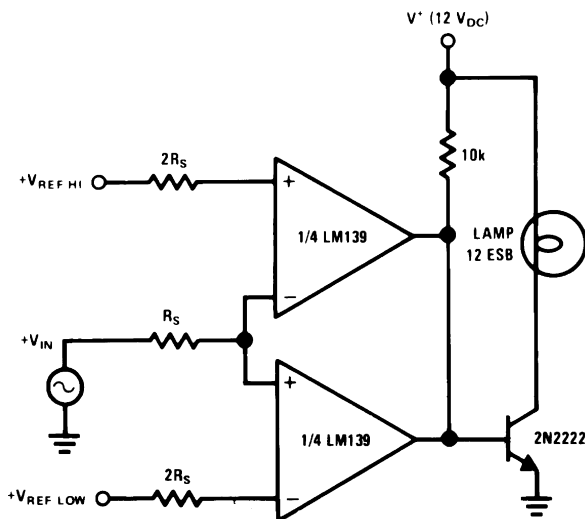


Figure 23. Limit Comparator

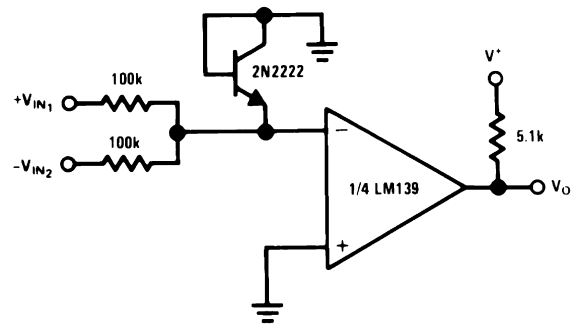
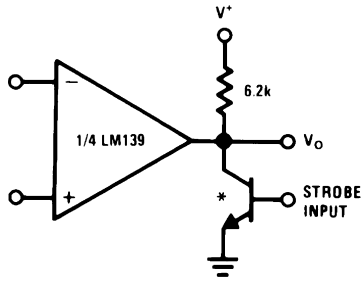


Figure 24. Comparing Input Voltages of Opposite Polarity



* Or open-collector logic gate without pull-up resistor

Figure 25. Output Strobing

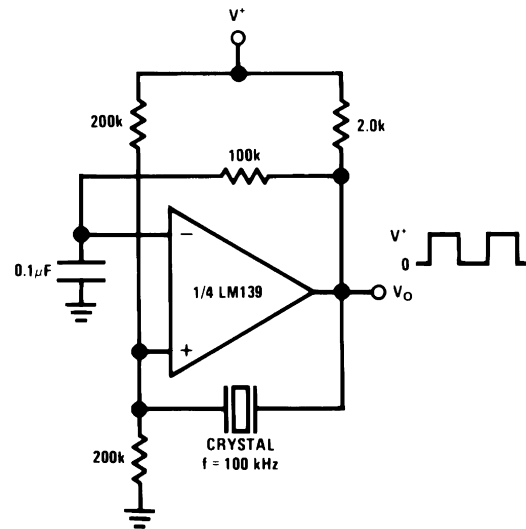


Figure 26. Crystal Controlled Oscillator

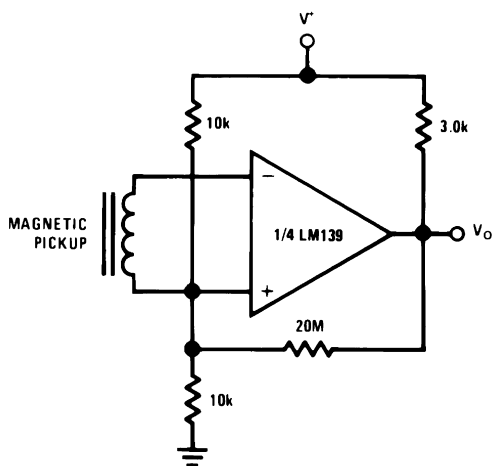


Figure 27. Transducer Amplifier

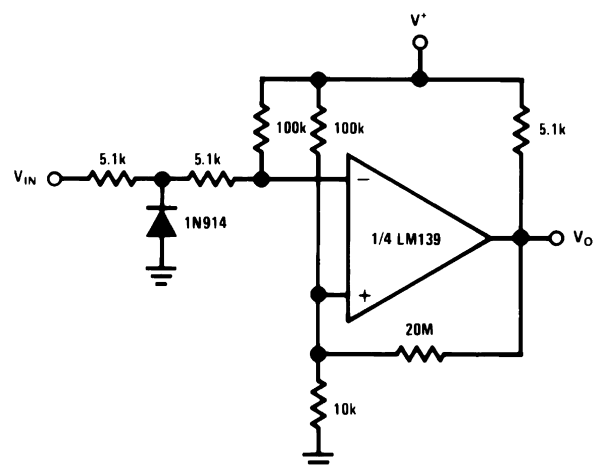
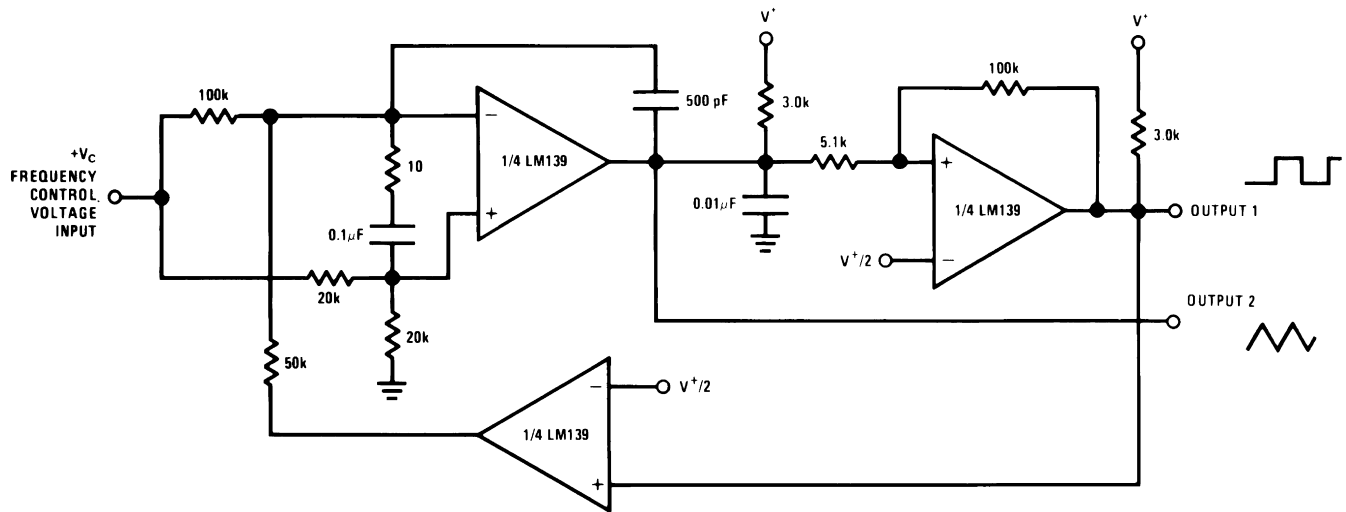


Figure 28. Zero Crossing Detector (Single Power Supply)



V⁺ = +30 V_{DC}
 250 mV_{DC} ≤ V_C ≤ +50 V_{DC}
 700 Hz ≤ f_O ≤ 100 kHz

Figure 29. Two-Decade High-Frequency VCO

Split-Supply Applications

($V^+ = +15\text{ V}_{DC}$ and $V^- = -15\text{ V}_{DC}$)

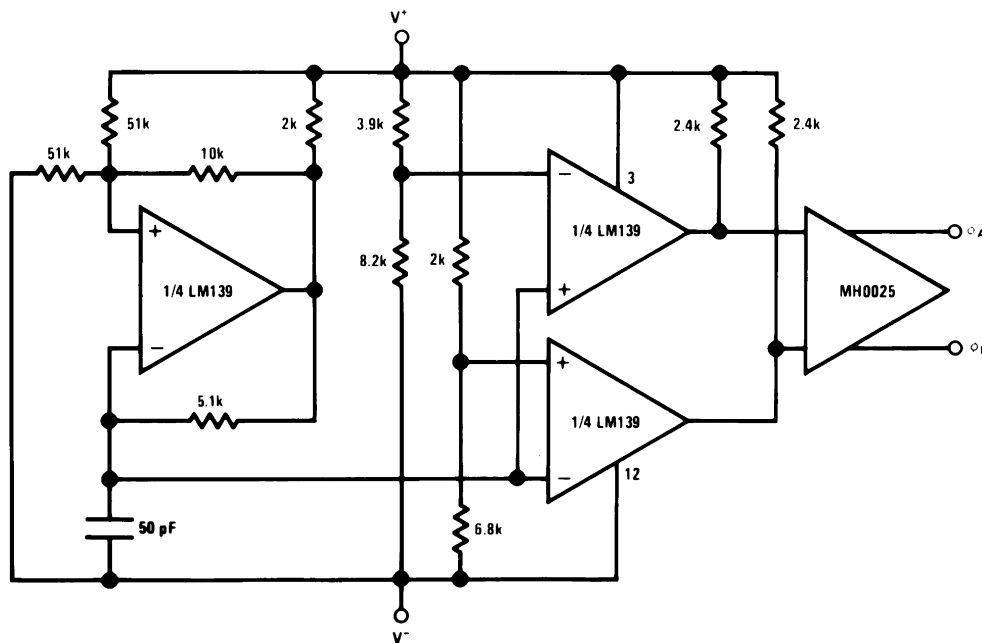


Figure 30. MOS Clock Driver

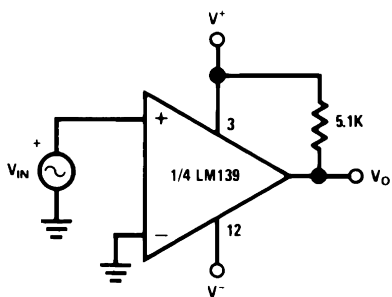


Figure 31. Zero Crossing Detector

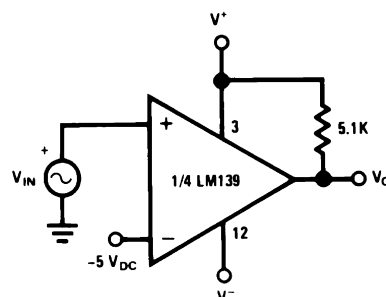


Figure 32. Comparator With a Negative Reference

REVISION HISTORY

Date Released	Revision	Section	Changes
02/15/05	A	New Release to corporate format	1 MDS datasheet converted into Corp. datasheet format. MJLM139-X rev 0D0. MDS datasheet will be archived.
10/26/2010	B	Order Information, Connection Diagrams, Absolute Ratings, Physical Dimensions drawings,	Update with current device information and format. Deleted J and WG pkg references. Revision A will be Archived
03/20/2013	B	All	Changed layout of National Data Sheet to TI format

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
JL139BDA	ACTIVE	CFP	NAD	14	19	TBD	Call TI	Call TI	-55 to 125	JL139BDA Q JM38510/ 11201BDA ACO 11201BDA >T	Samples
JM38510/11201BDA	ACTIVE	CFP	NAD	14	19	TBD	Call TI	Call TI	-55 to 125	JL139BDA Q JM38510/ 11201BDA ACO 11201BDA >T	Samples
M38510/11201BDA	ACTIVE	CFP	NAD	14	19	TBD	Call TI	Call TI	-55 to 125	JL139BDA Q JM38510/ 11201BDA ACO 11201BDA >T	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF LM139JAN, LM139JAN-SP :

- Military: [LM139JAN](#)
- Space: [LM139JAN-SP](#)

NOTE: Qualified Version Definitions:

- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

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